

NOT RECOMMENDED FOR NEW DESIGN USE DMC2053UVT



DMC2038LVT

COMPLEMENTARY PAIR ENHANCEMENT MODE MOSFET

Product Summary

Device	BV _{DSS}	R _{DS(ON)}	I _D T _A = +25°C
Q1	201/	$35m\Omega$ @ $V_{GS} = 4.5V$	4.5A
Q1 20V	56mΩ @ V _{GS} = 1.8V	3.5A	
Q2 -20V	$74mΩ @ V_{GS} = -4.5V$	-3.1A	
Q2	-20V	168mΩ @ $V_{GS} = -1.8V$	-2.0A

Description

This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Motor Control
- Power Management Functions
- DC-DC Converters
- Backlighting

Features

- Low On-Resistance
- Low Input Capacitance
- · Fast Switching Speed
- Low Input/Output Leakage
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

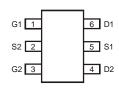
Mechanical Data

- Case: TSOT26
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 [©]
- Terminal Connections Indicator: See Diagram
- Weight: 0.013 grams (Approximate)

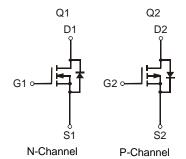


TSOT26





Top View Pin Configuration



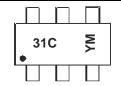
Ordering Information (Note 5)

Part Number	Compliance	Case	Packaging	
DMC2038LVT-7	Standard	TSOT26	3000/Tape & Reel	

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to https://www.diodes.com/quality/.
- 5. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



31C = Product Type Marking Code YM = Date Code Marking Y = Year (ex: F = 2018) M = Month (ex: 9 = September)

Date Code Key

Notes:

Date Odde Ney												
Year	201	7	2018		2019	20	20	2021		2022		2023
Code	E		F		G	ı	1	I		J		K
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings N-CHANNEL – Q1 (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Drain-Source Voltage			V _{DSS}	20	V
Gate-Source Voltage			V _{GSS}	±12	V
Continuous Drain Current (Note 6) V _{GS} = 4.5V State T		$T_A = +25$ °C $T_A = +70$ °C	I _D	3.7 3.0	А
		$T_A = +25$ °C $T_A = +70$ °C	I _D	4.1 3.2	А
Continuous Drain Current (Note 7) $V_{GS} = 4.5V$ $Steady State T_A = +25^{\circ}C T_A = +70^{\circ}C$ $t<10s T_A = +25^{\circ}C T_A = +70^{\circ}C$			I _D	4.5 3.6	А
		I _D	5.2 4.2	А	
Maximum Continuous Body Diode Forward Current	Is	1.5	Α		
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%	6)		I _{DM}	25	A

Maximum Ratings P-CHANNEL – Q2 (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Drain-Source Voltage			V _{DSS}	-20	V
Gate-Source Voltage			V _{GSS}	±12	V
Continuous Drain Current (Note 6) V _{GS} = -4.5V		T _A = +25°C T _A = +70°C	I _D	-2.6 -2.1	А
		$T_A = +25$ °C $T_A = +70$ °C	I _D	-2.9 -2.4	А
Continuous Drain Current (Note 7) $V_{GS} = -4.5V$ $Steady State T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$ $t<10s T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$		1 7 7	I _D	-3.1 -2.5	А
		I _D	-3.8 -3.0	А	
Maximum Continuous Body Diode Forward Current	Is	-1.5	Α		
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%	6)		I _{DM}	-17	А

Thermal Characteristics ($@T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic		Symbol	Value	Units
Total Dayor Dissination (Note 6)	T _A = +25°C	Б	0.8	W
Total Power Dissipation (Note 6)	$T_A = +70^{\circ}C$	P_D	0.5	VV
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	D	168	°C/W
Thermal Resistance, Junction to Ambient (Note 6)	t<10s	$R_{\theta JA}$	120	C/VV
Total Dayor Dissination (Note 7)	$T_A = +25$ °C	В	1.1	W
Total Power Dissipation (Note 7)	T _A = +70°C	P_D	0.7	VV
Thermal Resistance, Junction to Ambient (Note 7)	Steady State	Р	114	
Thermal Resistance, Junction to Ambient (Note 7)	t<10s	$R_{\theta JA}$	72	°C/W
Thermal Resistance, Junction to Case (Note 7)		$R_{ heta JC}$	39	
Operating and Storage Temperature Range		$T_{J_i}T_{STG}$	-55 to +150	°C

6. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout. 7. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

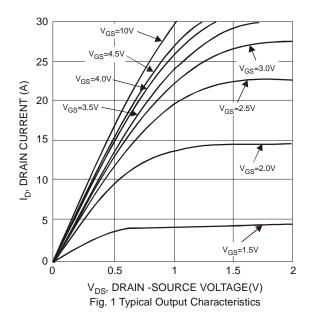


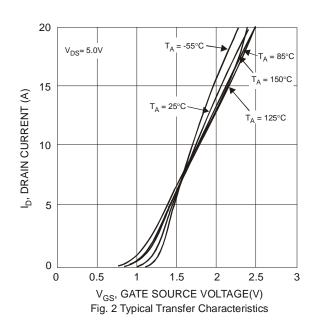
Electrical Characteristics N-CHANNEL - Q1 (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV _{DSS}	20	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current @T _C = +25°C	I _{DSS}	-	_	1.0	μA	$V_{DS} = 16V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 12V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V _{GS(TH)}	0.4	_	1.0	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$	
			27	35		$V_{GS} = 4.5V, I_D = 4.0A$	
Static Drain-Source On-Resistance	R _{DS(ON)}	_	33	43	mΩ	V _{GS} = 2.5V, I _D = 2.5A	
	-	_	43	56		V _{GS} = 1.8V, I _D = 1.5A	
Forward Transfer Admittance	Y _{fs}	_	9	_	S	$V_{DS} = 5V, I_{D} = 3.4A$	
Diode Forward Voltage	V _{SD}	0.4	_	1.1	V	V _{GS} = 0V, I _S = 1A	
DYNAMIC CHARACTERISTICS (Note 9)						•	
Input Capacitance	C_{iss}	_	400	530	pF	.,,	
Output Capacitance	Coss		70	90	pF	$V_{DS} = 10V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance	C_{rss}		65	100	pF	1 = 1.000112	
Gate Resistance	R_g	_	1.9	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Qg	_	5.7	_	nC		
Total Gate Charge (V _{GS} = 10V)	Qg	_	12	17	nC	15)/ 1504	
Gate-Source Charge	Q _{gs}	_	0.7	_	nC	$V_{DS} = 15V, I_{D} = 5.8A$	
Gate-Drain Charge	Q_{gd}	_	1.4	_	nC		
Turn-On Delay Time	t _{D(ON)}	_	5	10	ns		
Turn-On Rise Time	t _R	_	8	16	ns	$V_{DS} = 10V, V_{GS} = 4.5V,$	
Turn-Off Delay Time	t _{D(OFF)}	_	25	40	ns	$R_G = 6\Omega$, $I_{DS} = 1A$	
Turn-Off Fall Time	t _F	_	8	16	ns		

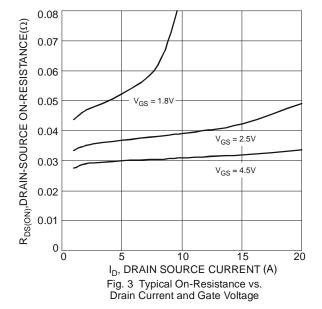
Notes: 8. Short duration pulse test used to minimize self-heating effect.

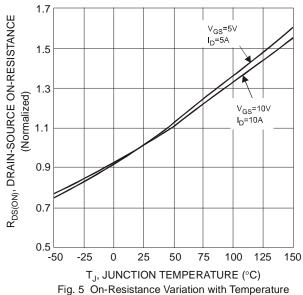
9. Guaranteed by design. Not subject to product testing.











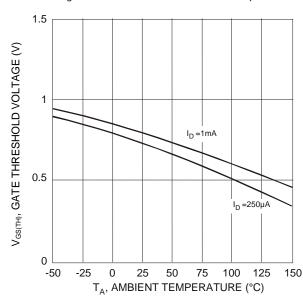
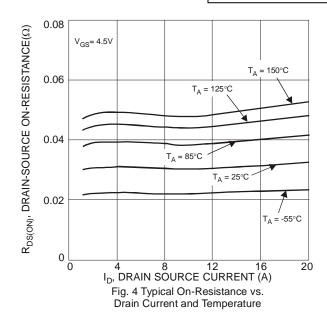
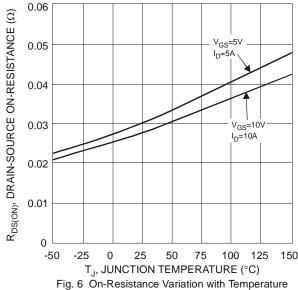
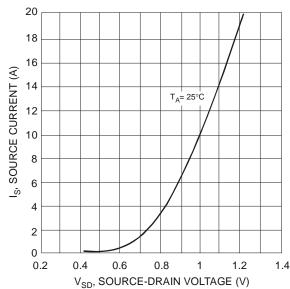


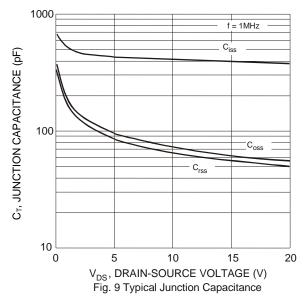
Fig. 7 Gate Threshold Variation vs. Ambient Temperature

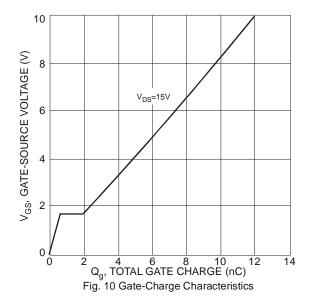


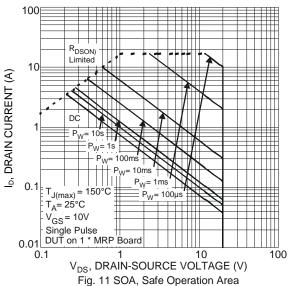












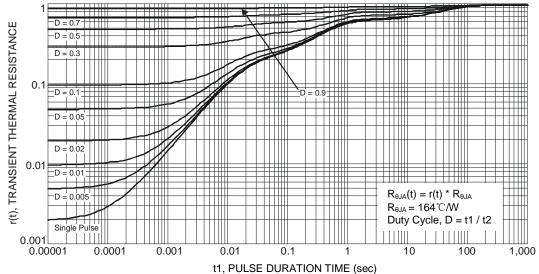


Fig. 12 Transient Thermal Resistance

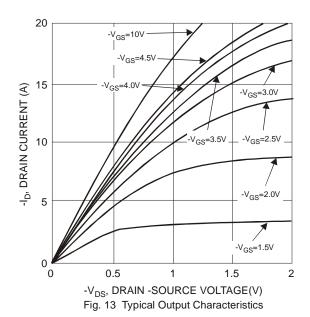


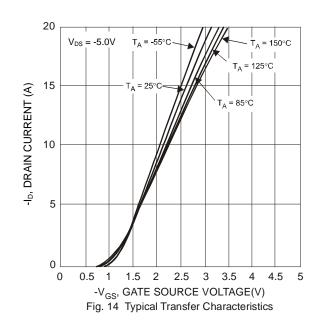
Electrical Characteristics P-CHANNEL - Q2 (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV _{DSS}	-20	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current @T _C = +25°C	I _{DSS}	_	_	-1.0	μA	V _{DS} = -16V, V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 12V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V _{GS(TH)}	-0.4	_	-1.0	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
		_	57	74		$V_{GS} = -4.5V$, $I_D = -3.0A$	
Static Drain-Source On-Resistance	R _{DS(ON)}	_	76	110	mΩ	V _{GS} = -2.5V, I _D = -1.5A	
		_	102	168		V _{GS} = -1.8V, I _D = -1.0A	
Forward Transfer Admittance	Y _{fs}	_	10	_	S	$V_{DS} = -5V, I_{D} = -3.0A$	
Diode Forward Voltage	V _{SD}	_	-0.8	-1.0	V	V _{GS} = 0V, I _S = -0.6A	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	C _{iss}	_	530	705	pF		
Output Capacitance	Coss	_	70	95	pF	$V_{DS} = -10V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance	C_{rss}		60	90	pF	1 = 1.00012	
Gate Resistance	R_g	_	72	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = -4.5V)	Qg	_	7	10	nC		
Total Gate Charge (V _{GS} = -10V)	Qg	_	14	_	nC	151/ 1 00	
Gate-Source Charge	Q _{gs}	_	0.95	_	nC	$V_{DS} = -15V, I_{D} = -6A$	
Gate-Drain Charge	Q_{gd}	_	1.2	_	nC		
Turn-On Delay Time	t _{D(ON)}	_	11	20	ns		
Turn-On Rise Time	t _R		12	22	ns	$V_{DS} = -10V, V_{GS} = -4.5V,$	
Turn-Off Delay Time	t _{D(OFF)}		21	34	ns	$R_G = 6\Omega$, $I_S = -1A$	
Turn-Off Fall Time	t _F	_	13	23	ns		

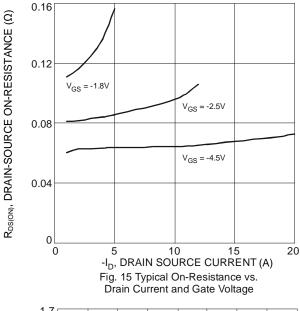
Notes: 8. Short duration pulse test used to minimize self-heating effect.

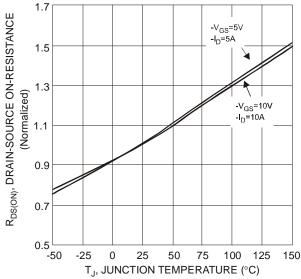
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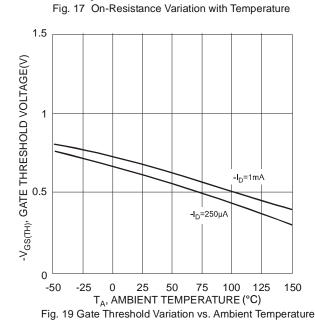


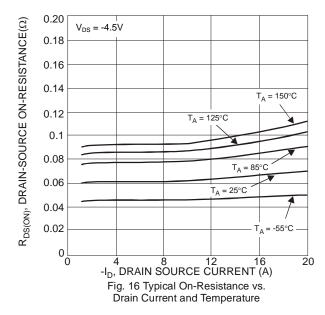


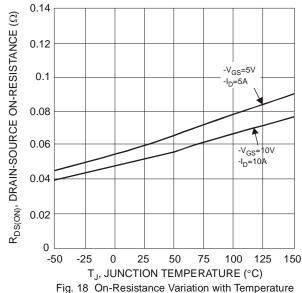


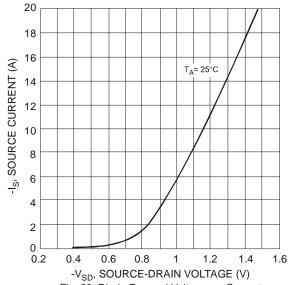




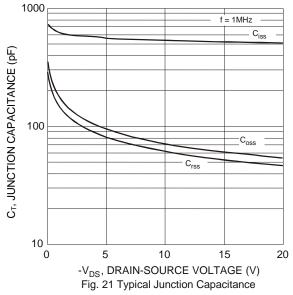


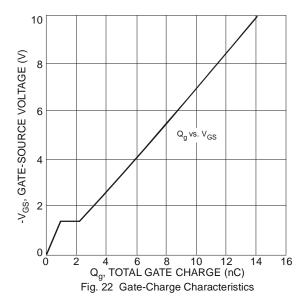


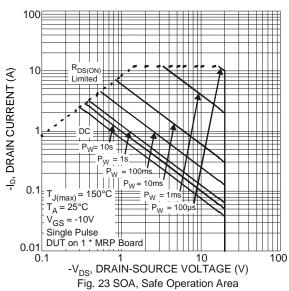


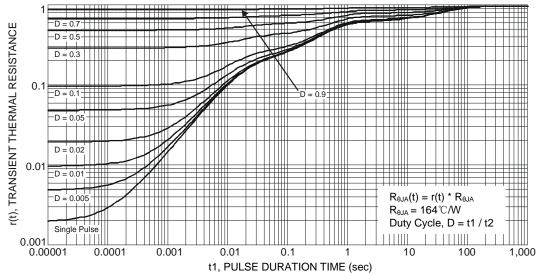










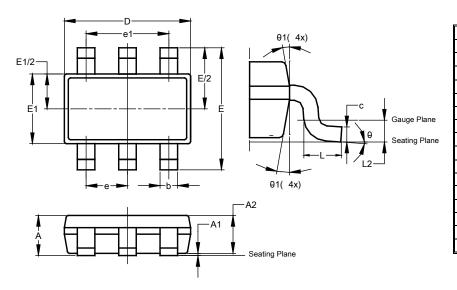




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

TSOT26

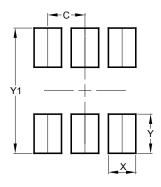


TSOT26							
Dim	Min Max Typ						
Α	-	1.00	-				
A1	0.010	0.100	-				
A2	0.840	0.900	-				
D	2.800	3.000	2.900				
Е	2.800 BSC						
E1	1.500	1.600					
b	0.300	0.450	_				
С	0.120	1					
е	0.950 BSC						
e1	1	.900 BS	C				
L	0.30 0.50 -						
L2	0	.250 BS	С				
θ	0° 8° 4°						
θ1	4°	12°	-				
Α	II Dimen	sions in	mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

TSOT26



Dimensions	Value (in mm)
С	0.950
Х	0.700
Y	1.000
Y1	3 199



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